

REMARKS

Re-examination of the above mentioned application is hereby requested in view of the above amendments and remarks which follow. Applicants appreciate the Examiner's thorough consideration of the above-identified application, and in the acknowledgement of allowable subject matter. In response to the Examiner's request, Applicants submit the following amendments and remarks.

The Examiner rejected claims 12-15 and 17-18 under 37 U.S.C. §102(b) as being anticipated by Chan et al. The Examiner indicates that Chan discloses an LGA interconnect (in Fig. 2) for interconnection to further electrical components, said LGA interconnect comprising: a substrate (36, 36a) having an array of contact receiving openings (37) and the substrate having a receiving aperture (38) the receiving aperture having a receiving portion which transitions into a locking portion (38a), a plurality of contact assemblies positioned and retained in said substrate (Fig. 4); a frame housing (Fig. 6) positioned around a periphery of said substrate (Fig. 1b); alignment members (78) projecting from said substrate (3), and extending through said frame housing for aligning said substrate relative to at least one of the electrical components, the alignment members being insertable into said receiving openings and locked in place in said locking portion (Figs. 3 and 4). Applicants respectfully disagree with the characterization of Chan as it relates to applicants' invention.

This is the exact type of interconnection that applicants have improved upon. In Chan, the contacts are positioned on modules 10 and 10A yet the modules have no means for aligning the contacts directly with the integrated circuit chip. Granted, Chan includes a pair of module locator assemblies 36 and 36A, however the addition of these module locators adds to the tolerance stack up of the assembly.

However, Applicants have amended Claim 12 to indicate that the LGA interconnect has a substrate (which is shown at reference number 6 in Fig. 3), and includes a plurality of contact assemblies 8. The substrate includes a receiving aperture (reference number 72 shown in Fig. 8), having a receiving portion which transitions into a locking portion 80. A frame 4A, 4B is positioned around a periphery of the substrate and finally aligning members 150 project from the substrate (as best shown in Fig. 18) and extend through the frame housing as best shown in Fig. 21 to align the substrate relative to at least

one electrical component. the alignment members being insertable into said receiving opening and locked in place **to said substrate by** said locking portion.

Thus, rather than having plural members, to which and through which, alignment members are assembled as in Chan, applicants having provided the alignment members 150 locked in place on the same substrate as that which contains the contact elements 8. In this manner, the contact assemblies can be precisely aligned with further electrical components. Thus there is no anticipation of applicants' Claim 12 by Chan nor is there any suggestion to modify it to include such an assembly. Furthermore, applicants believe that Claims 12 through 26 are allowable as amended and respectfully request early passage thereof.

In the event that Applicants have overlooked the need for an extension of time or a payment of fee, Applicants hereby conditionally petition therefore and authorize that any charges be made to Deposit Account No. 02-0390, BAKER & DANIELS.



Eric J. Groen, Reg. No. 32,230
Attorney for Applicants
BAKER & DANIELS LLP
300 North Meridian Street, Suite 2700
Indianapolis, IN 46204
Telephone: (317) 237-1066
Fax: (317) 237-1000

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Eric J. Groen